

General Description

The WSF40P03 is the highest performance trench P-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSF40P03 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

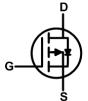
BVDSS	RDSON	ID
-30V	18mΩ	-40A

Applications

- Power Magagement in Desktop
- DC/DC Converters.
- Load Switch

TO-252 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	±25	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V	-40	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V	-25	Α
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V	-9.6	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V	-7.7	Α
I _{DM} ^a	Pulsed Drain Current	-160	Α
E _{AS} ^b	Single Pulse Avalanche Energy	28	mJ
I _{AS} b	Avalanche Current	-20	Α
P _D @T _A =25℃	Total Power Dissipation	2.5	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}^{c}$	Thermal Resistance Junction-Ambient		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case		2.9	°C/W

Note a : Pulse width limited by max. junction temperature.

Note b: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_i=25°C).

Note c : Surface Mounted on 1in² pad area.



Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25 $^{\circ}$ C , I _D =-1mA		-0.022		V/℃
D d	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-20A		15	18	mΩ
R _{DS(ON)} d		V _{GS} =-4.5V , I _D =-15A		20	26	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.6	-2.5	V
	Drain-Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			-1	- uA
I _{DSS}		V _{DS} =-24V , V _{GS} =0V , T _J =55℃			-5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.5		Ω
Q_g	Total Gate Charge	\\ - 45\\ \\ - 45\\		11		nC
Q _{gs}	Gate-Source Charge	V_{DS} =-15V, V_{GS} =-4.5V, I_{DS} =-20A		5		
Q _{gd}	Gate-Drain Charge			5		
T _{d(on)}	Turn-On Delay Time			11	20	
Tr	Rise Time	V_{DD} =-15V, R _L =15 Ω , I_{DS} =-1A, V_{GEN} =-10V, R_{G} =6 Ω		10	18	
T _{d(off)}	Turn-Off Delay Time			39	70	ns
T _f	Fall Time			29	53	
C _{iss} e	Input Capacitance	V_{GS} =0V, V_{DS} =-15V, Frequency=1.0MHz		1256	1633	
C _{oss} e	Output Capacitance			187		pF
C _{rss} ^e	Reverse Transfer Capacitance			115		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V , Force Current			-20	Α
V _{SD} ^d	Diode Forward Voltage	V _{GS} =0V , I _S =-1A			-1.2	V
t _{rr}	Reverse Recovery Time	-IF=-20A , dl/dt=100A/μs		12		nS
Q _{rr}	Reverse Recovery Charge			3.5		nC

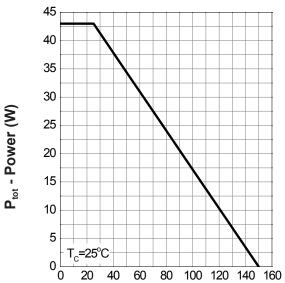
Note d : Pulse test ; pulse width≤300 μ s, duty cycle≤2%.

Note e: Guaranteed by design, not subject to production testing.



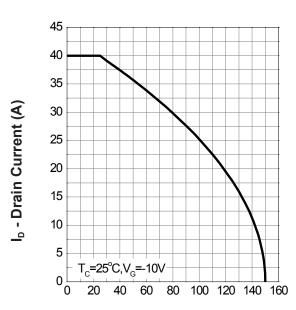
Typical Operating Characteristics

Power Dissipation



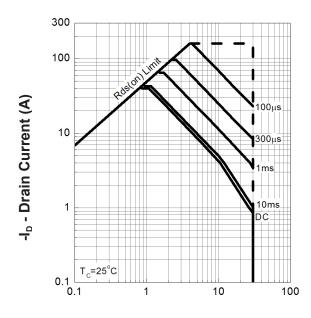
T_i - Junction Temperature (°C)

Drain Current



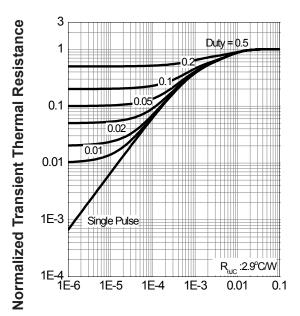
T_i - Junction Temperature (°C)

Safe Operation Area



-V_{DS} - Drain - Source Voltage (V)

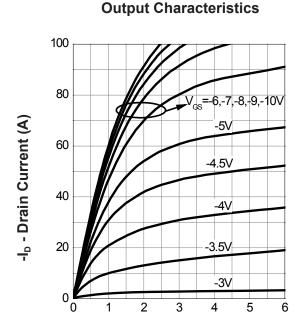
Thermal Transient Impedance



Square Wave Pulse Duration (sec)

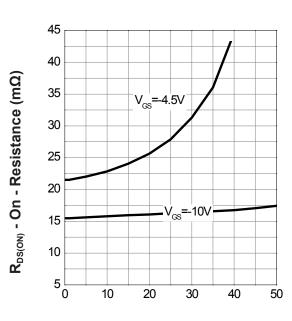


Typical Operating Characteristics(Cont.)



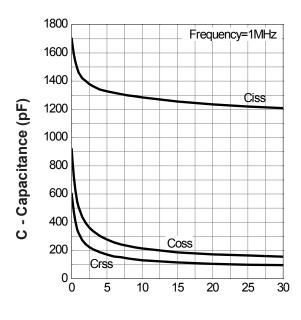
-V_{DS} - Drain - Source Voltage (V)

Drain-Source On Resistance



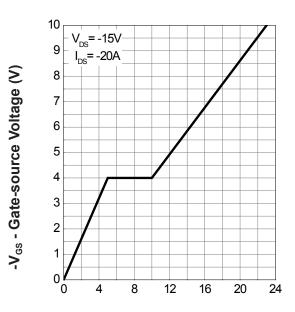
-I_D - Drain Current (A)

Capacitance



-V_{DS} - Drain-Source Voltage (V)

Gate Charge

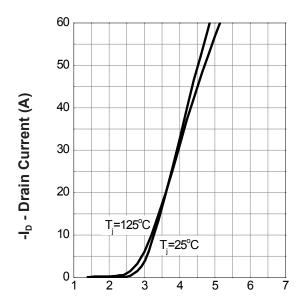


Q_G - Gate Charge (nC)



Typical Operating Characteristics(Cont.)

Transfer Characteristics



-V_{GS} - Gate-Source Voltage (V)



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